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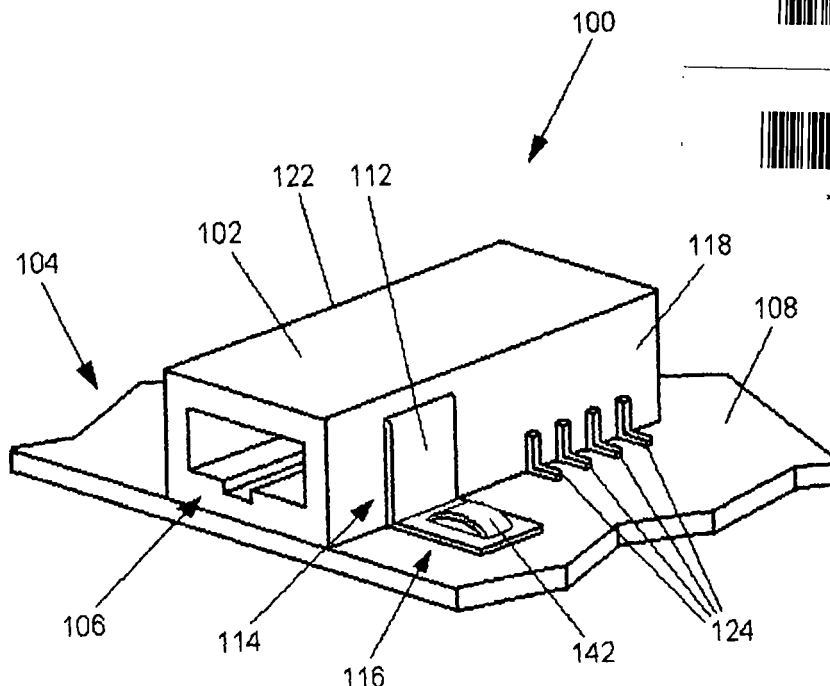
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(54) Title: SURFACE MOUNT CONNECTOR LEAD



162162



ACTION

(57) Abstract: An enhanced joint thickness lead used for surface mounting electronic devices to a substrate, wherein a portion of the enhanced joint thickness lead that is substantially parallel to the substance. The enhanced joint thickness lead includes an arcuate structure, which provides an enhanced joint thickness for the solder used to connect the lead to the substrate. The enhanced joint thickness of the solder results in a more robust attachment of the electronic device.

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